

# Baseband Schematic

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19. M1/M2
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22. CODEC HI6403
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25. MIC/REC/HAC/HIFI
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# MODEM Schematic

31. RF Interface
32. APT\_LM3243
33. RFIC0\_Hi6363
34. DPDT\_Connector
35. TXM
36. MMBPA
37. TX\_Loadpull
38. TRX\_LB\_1
39. TRX\_LB\_2
40. TRX\_MB\_1
41. TRX\_MB\_2
42. TRX\_HB\_1
43. TRX\_HB\_2
44. PRX\_LNA\_Module
45. DRX\_SWITCH
46. DRX\_LB
47. DRX\_MB
48. DRX\_HB
49. DRX\_LNA\_Module
50. Reserved
51. Reserved
52. Reserved
53. Reserved
54. Reserved
55. Reserved
56. Reserved
57. Reserved
58. Reserved
59. Reserved
60. NC\_POWER
61. NC\_BB
62. NC\_FE\_WIFI\_2G
63. NC\_FE\_WIFI\_5G
64. NC\_GPS
65. RES
66. NFC Antena
67. RES
68. NFC\_BB
69. RES
70. Antenna
71. NFC Antena

The type and specification of the components refer to the BOM

				NA	2018-01-19
				ECA NO	DATE
DESIGNED	liujiaxin 00251228	HL1COLM		03024XLP_SCHZH	
REVIEWED	wangxiaoyang 00209659				
		VER	PART_NUMBER	SHEET 1 OF 71	
		C	03024XLP	HUAWEI TECH CO.,LTD.	

# 2.RES

A

A

B

B

C

C

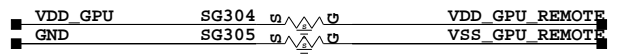
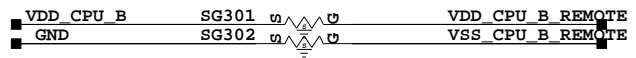
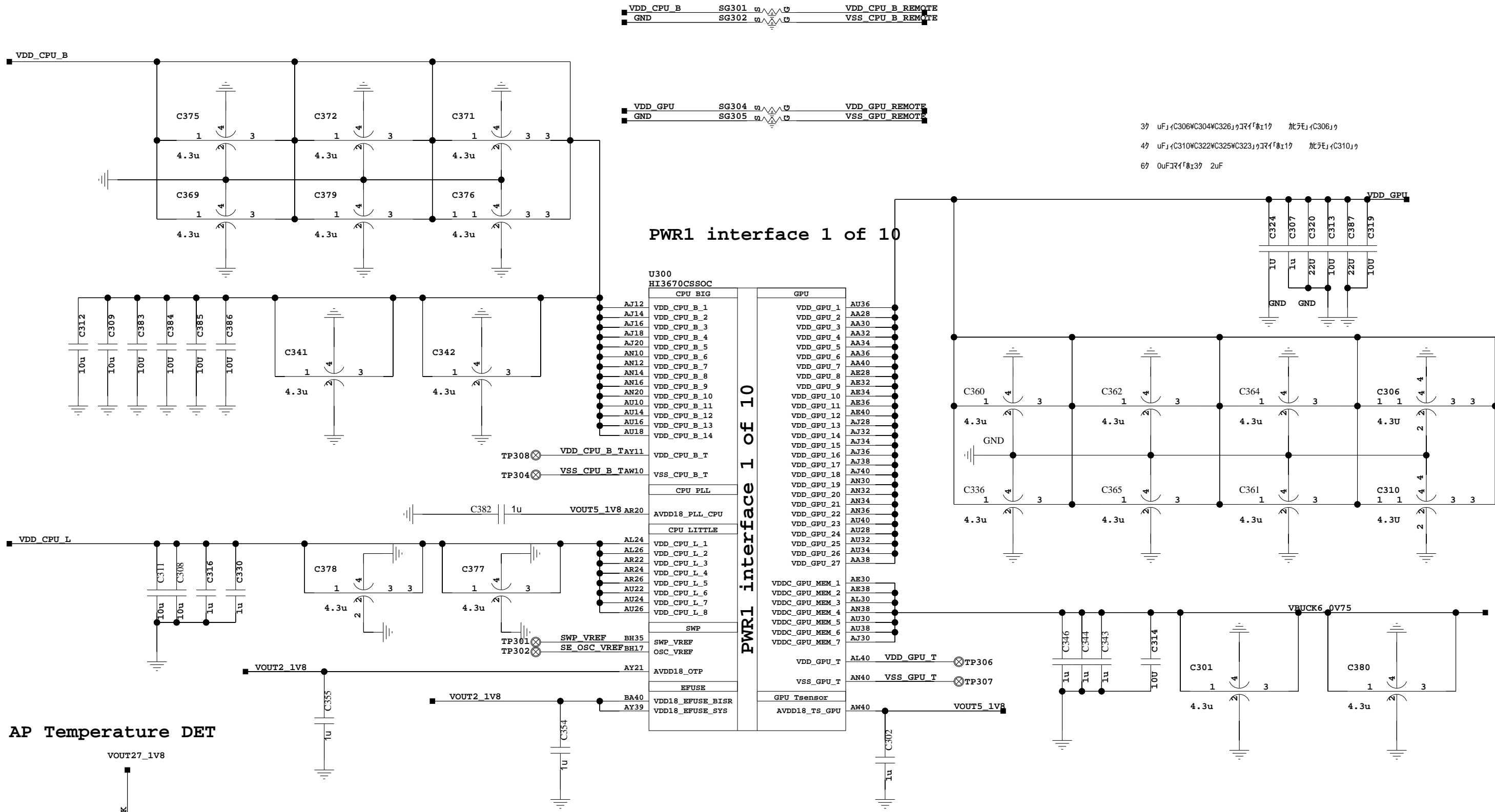
D

D

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REVIEWED	wangxiaoyang 00209659				
		VER	PART_NUMBER	SHEET 2 OF 71	
		C	03024XLP	HUAWEI TECH CO.,LTD.	

# 3.SOC PWR1



3) uF, C306#C304#C326の配列に注意し、配列にC306の  
 4) uF, C310#C322#C325#C323の配列に注意し、配列にC310の  
 6) 0uFの配列に注意し、2uF

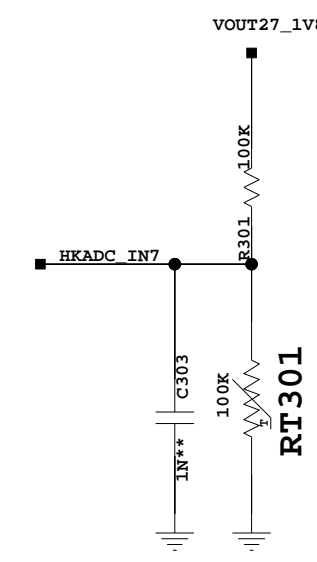
PWR1 interface 1 of 10

U300  
HI3670CSSOC

CPU BIG		GPU	
AJ12	VDD_CPU_B_1	AU36	VDD_GPU_1
AJ14	VDD_CPU_B_2	AA28	VDD_GPU_2
AJ16	VDD_CPU_B_3	AA30	VDD_GPU_3
AJ18	VDD_CPU_B_4	AA32	VDD_GPU_4
AJ20	VDD_CPU_B_5	AA34	VDD_GPU_5
AN10	VDD_CPU_B_6	AA36	VDD_GPU_6
AN12	VDD_CPU_B_7	AA40	VDD_GPU_7
AN14	VDD_CPU_B_8	AE28	VDD_GPU_8
AN16	VDD_CPU_B_9	AE32	VDD_GPU_9
AN20	VDD_CPU_B_10	AE34	VDD_GPU_10
AU10	VDD_CPU_B_11	AE36	VDD_GPU_11
AU14	VDD_CPU_B_12	AE40	VDD_GPU_12
AU16	VDD_CPU_B_13	AJ28	VDD_GPU_13
AU18	VDD_CPU_B_14	AJ32	VDD_GPU_14
	VDD_CPU_B_T	AJ34	VDD_GPU_15
	VSS_CPU_B_T	AJ36	VDD_GPU_16
		AJ38	VDD_GPU_17
		AJ40	VDD_GPU_18
		AN30	VDD_GPU_19
		AN32	VDD_GPU_20
		AN34	VDD_GPU_21
		AN36	VDD_GPU_22
		AU40	VDD_GPU_23
		AU28	VDD_GPU_24
		AU32	VDD_GPU_25
		AU34	VDD_GPU_26
		AA38	VDD_GPU_27
		AE30	VDDC_GPU_MEM_1
		AE38	VDDC_GPU_MEM_2
		AL30	VDDC_GPU_MEM_3
		AN38	VDDC_GPU_MEM_4
		AU30	VDDC_GPU_MEM_5
		AU38	VDDC_GPU_MEM_6
		AJ30	VDDC_GPU_MEM_7
		AL40	VDD_GPU_T
		AN40	VSS_GPU_T
		AW40	AVDD18_TS_GPU

PWR1 interface 1 of 10

AP Temperature DET



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		VER	PART_NUMBER	SHEET 3 OF 71
		C	03024XLP	HUAWEI TECH CO.,LTD.

NA 2018-01-19  
 ECA NO DATE

03024XLP\_SCHZH

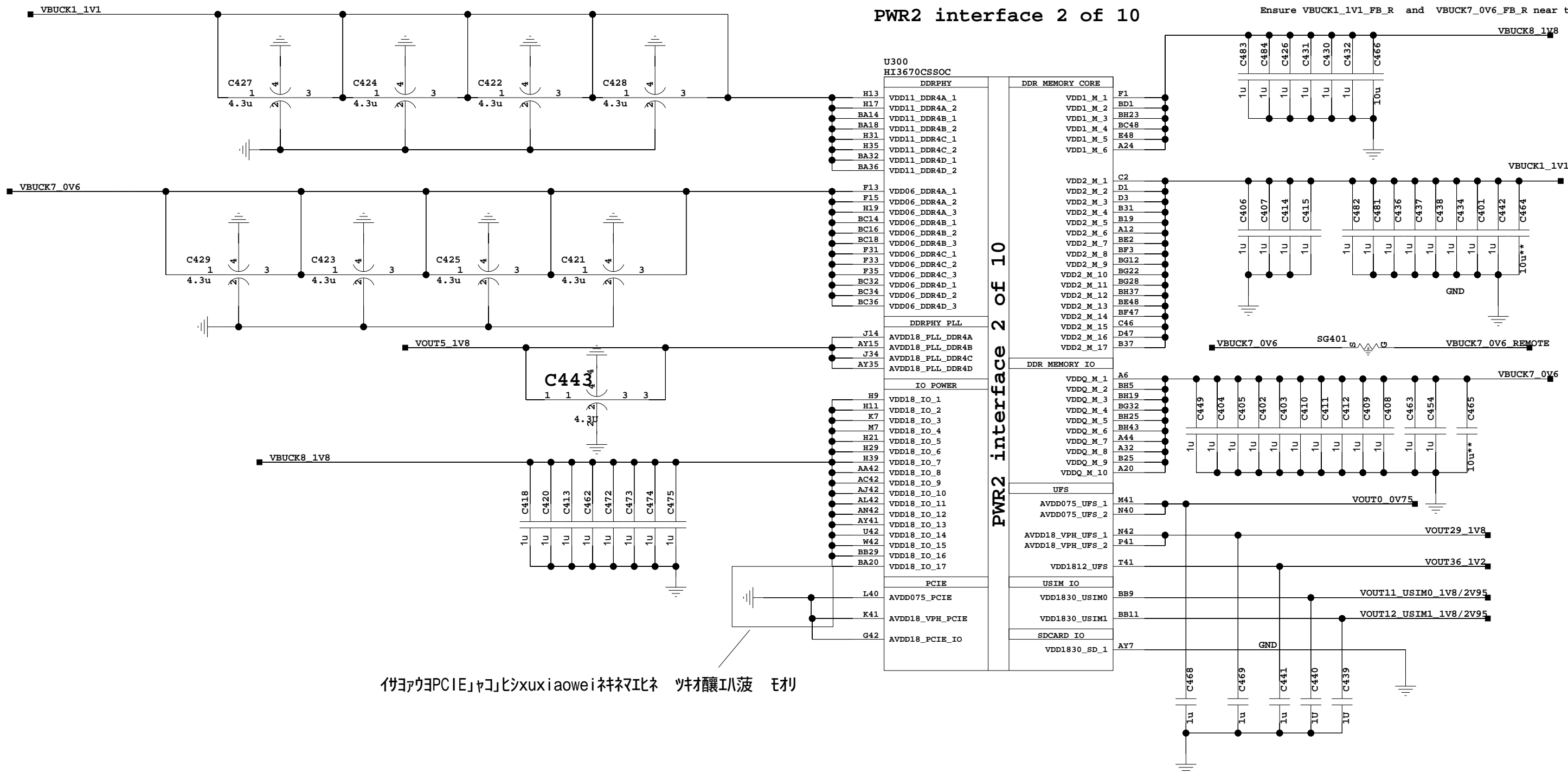
SHEET 3 OF 71

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# 4.SOC PWR2

## PWR2 interface 2 of 10

Ensure VBUCK1\_1V1\_FB\_R and VBUCK7\_0V6\_FB\_R near the CAP



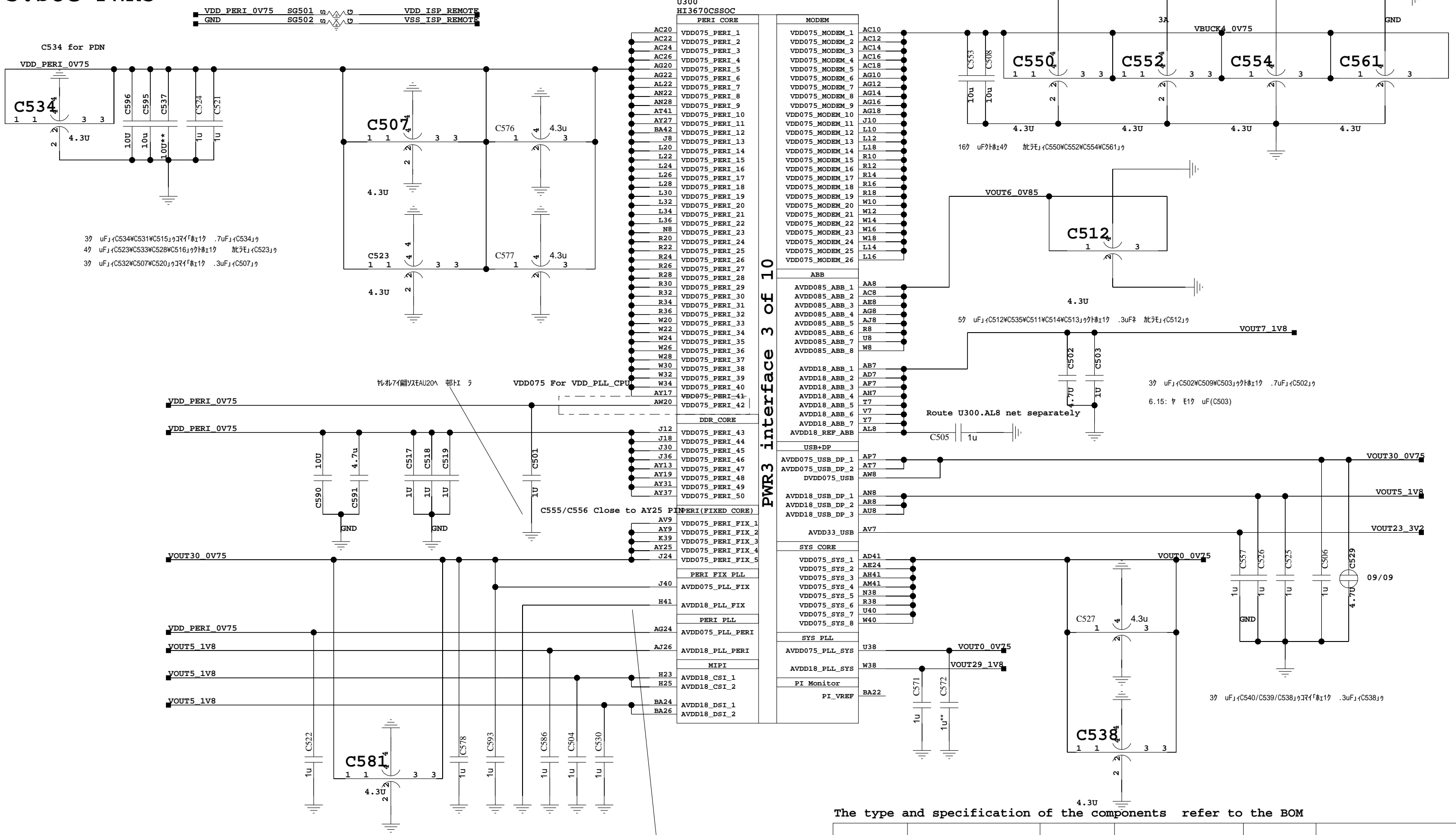
PCIEにxuxiaoweいネナマレニ 波ノ醸子 利モ

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				NA	2018-01-19
				ECA NO	DATE
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REVIEWED	wangxiaoyang 00209659				
		VER	PART_NUMBER	SHEET 4 OF 71	
		C	03024XLP	HUAWEI TECH CO.,LTD.	

# 5.SOC PWR3

## PWR3 interface 3 of 10



この図はPCIEの電源配線を示しています。xuxiaowei様にご提供の資料に基づいて作成されています。

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		C	HUAWEI TECH CO.,LTD.
			NA 2018-01-19
			ECA NO DATE